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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/735,668	12/16/2003	Dov Moran	246/234	2836
75	90 03/16/2006	EXAMINER NORRIS, JEREMY C		
	RIEDMAN LTD.			
C/o Bill Polking Discovery Dispa		ART UNIT	PAPER NUMBER	
9003 Florin Way Upper Marlboro, MD 20772			2841	
			DATE MAILED: 03/16/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)			
Office Action Summary		10/735,668	MORAN, DOV			
		Examiner	Art Unit			
		Jeremy C. Norris	2841			
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the c	orrespondence address			
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).						
Status						
2a)⊠	Responsive to communication(s) filed on <u>03 January 2006</u> . This action is FINAL . 2b) This action is non-final. Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Dispositi	on of Claims					
5)□ 6)⊠ 7)□ 8)□ Applicati 9)□	Claim(s) 1-16 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw Claim(s) is/are allowed. Claim(s) 1-16 is/are rejected. Claim(s) is/are objected to. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or ion Papers The specification is objected to by the Examine. The drawing(s) filed on 16 December 2003 is/are Applicant may not request that any objection to the or	vn from consideration. r election requirement. r. re: a)⊠ accepted or b)□ objected drawing(s) be held in abeyance. See	e 37 CFR 1.85(a).			
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority ι	ınder 35 U.S.C. § 119					
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
2) 🔲 Notic 3) 🔲 Inforr	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal Pa 6) Other:				

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DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-4, 6, 13, 15, and 16 are rejected under 35 U.S.C. 102(b) as being anticipated by US 5,569,955 (Chillara).

Chillara discloses, referring primarily to figures 2 and 2A, an electronic module (30), comprising; electronic circuitry (44); a first connection mechanism (42), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and a second connection mechanism (48), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a second method different from said first method [claim 1], wherein said first method is robotic mounting and said second method is manual mounting [claim 2], wherein said first connection mechanism is directly operationally connected to said electronic circuitry (figure 2A) [claim 3], wherein said second connection mechanism is directly operationally connected to said electronic circuitry (figure 2) [claim 4], wherein said second connection mechanism is directly operationally connected to said electronic circuitry [claim 6], further comprising an electrically insulating body (34) whereon said electronic circuitry, said first connection mechanism and said second connection mechanism are mounted [claim 13].

Similarly, Chillara discloses, an electronic module (30), comprising; electronic circuitry (44); a first connection mechanism (42), directly operationally connected to said electronic circuitry (figure 2), for mounting of the electronic module by a first method; and a second connection mechanism (48), directly operationally connected to said electronic circuitry (figure 2A), for mounting of the electronic module on a printed circuit board by a second method different from said first method [claim 15].

Moreover, Chillara discloses, an electronic module (30), comprising; electronic circuitry (44); a first connection mechanism (42), operationally connected to said electronic circuitry (figure 2), for mounting of the electronic module by a first method; and a second connection mechanism (48), operationally connected to said electronic circuitry (figure 2A), for mounting of the electronic module on a printed circuit board by a second method different from said first method, and an electrically insulating body (36) whereon said electronic circuitry, said first connection mechanism and said second connection mechanism are mounted [claim 16].

Claims 1-3 and 5-13 are rejected under 35 U.S.C. 102(b) as being anticipated by US 6,020,629 (Farnworth).

Farnworth discloses, referring primarily to figures 2C & D, an electronic module, comprising; electronic circuitry (20); first connection mechanism (40), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and a second connection mechanism (42), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed

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circuit board by a second method different from said first method [claim 1], wherein said first method is robotic mounting and said second method is manual mounting [claim 2], wherein said first connection mechanism is directly operationally connected to said electronic circuitry [claim 3], wherein said second connection is operationally connected to said electronic circuitry via said first mechanism connection mechanism [claim 5].

Alternately, Farnworth discloses, referring primarily to figure 10, an electronic module, comprising; electronic circuitry (20); first connection mechanism (42), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and a second connection mechanism (40), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a second method different from said first method [claim 1], wherein said second connection mechanism is directly operationally connected to said electronic circuitry [claim 6], wherein said second connection is operationally connected to said electronic circuitry via said first mechanism connection mechanism [claim 7], wherein first connection mechanism includes at least one substantially hemispherical solder ball (col. 5, lines 15-20) [claim 8], wherein said second connection mechanism includes at least one electrically conducting pad (col. 5, lines 15-20) [claim 9], wherein said at least one solder ball and said at least one pad are like in number [claim 10], further comprising: for each said solder ball, and for a respective said pad, a respective wire (44) operationally connecting said each solder ball to said respective pad [claim 11], wherein said second connection mechanism includes at least one electrically conducting pad (col. 5, lines 15-20) [claim 12], further

comprising an electrically insulating body (12) whereon said electronic circuitry, said first connection mechanism and said second connection mechanism are mounted [claim 13].

Claims 1, 13, and 14 are rejected under 35 U.S.C. 102(b) as being anticipated by US 5,481,133 (Hsu).

Hsu discloses, referring primarily to figures 1-5, an electronic module, comprising; electronic circuitry (48); first connection mechanism (24), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and a second connection mechanism (46), operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a second method different from said first method [claim 1], further comprising an electrically insulating body (40) whereon said electronic circuitry, said first connection mechanism and said second connection mechanism are mounted [claim 13], wherein both said first connection mechanism and said second connection mechanism are mounted on a common side of said body (fig. 5) [claim 14].

Response to Arguments

Applicant's arguments with respect to claims 1-16 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. US 6,093,029, granted to Kwon et al., discloses an electronic module capable of being mounted by two different methods.

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Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

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A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jeremy C. Norris whose telephone number is 571-272-1932. The examiner can normally be reached on Monday - Friday, 9:30 am - 5:30 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kamand Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

JCSN

SUPERVISORY PATENT EXAMINER **TECHNOLOGY CENTER 2800**